



# Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

**Adobe Reader version 7.0.5 is required to complete this declaration.**

IPC-1752-1 v1.02  
1752-1

IPC Web Site for Information on IPC-1752 Standard  
<http://www.ipc.org/IPC-175x>

**Form Type \***  
**Distribute**

**Declaration Class \***  
**Class 4 - RoHS Yes/No, JIG Format Substances, Mfg Info**

## Supplier Information

<b>Company Name *</b> Anaren Microwave, Inc.	Company Unique ID	Unique ID Authority	<b>Response Date *</b> 2007-06-22	Response Document ID				
<b>Contact Name *</b> Michael Lugert	Title - Contact Product Line Manager	<b>Phone - Contact *</b> (315) 432-8909 x1480	<b>Email - Contact *</b> mlugert@anaren.com		Duplicate Contact -> Authorized Representative			
<b>Authorized Representative *</b> Michael Lugert	Title - Representative Product Line Manager	<b>Phone - Representative *</b> (315) 432-8909 x1480	<b>Email - Representative *</b> mlugert@anaren.com		Supplier Comments or URL for Additional Information			
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight	UOM	Unit Type
	<b>XC0900A-05P</b>	<b>5dB Xinger II Coupler, 0.8-1.0</b>			<b>East Syracuse</b>	<b>0.42</b>	<b>g</b>	<b>Each</b>
Alternate Recommendation	<b>XC0900A-05S</b>	<b>5dB Xinger II Coupler, 0.8-1.0</b>	Alternate Item Comments					

## Manufacturing Process Information

Terminal Plating / Grid Array Material <b>Tin/Lead (Sn63Pb37)</b>	Terminal Base Alloy <b>CU Alloy</b>	J-STD-020 MSL Rating <b>1</b>	Peak Process Body Temperature <b>260 C</b>	Max Time at Peak Temperature <b>30 seconds</b>	Number of Reflow Cycles
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Comments

Save the fields in this form to a file

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Lock Supplier Fields

### RoHS Material Composition Declaration

Declaration Type \*

Custom

**RoHS Directive 2002/95/EC** **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Enter your statement here: See Attachment Below

**RoHS Declaration \*** 3 - Item(s) does not contain RoHS restricted substances per the definition above except for lead in solders and selected exemptions, if any

Supplier Acceptance **Accepted**

**Exemptions:** The items on this form meet the specifications of the RoHS Definition above, except for the following application-specific exemptions. Check the appropriate boxes below for the applicable exemptions for the item.

- |  |   |
|--|---|
| <input type="checkbox"/> <b>1.</b> Mercury in compact fluorescent lamps not exceeding 5 mg per lamp<br><input type="checkbox"/> <b>2a.</b> Mercury in straight fluorescent lamps for general purposes not exceeding 10 mg in halophosphate lamps<br><input type="checkbox"/> <b>2b.</b> Mercury in straight fluorescent lamps for general purposes not exceeding 5 mg in triphosphate lamps with a normal lifetime<br><input type="checkbox"/> <b>2c.</b> Mercury in straight fluorescent lamps for general purposes not exceeding 8 mg in triphosphate with long lifetime<br><input type="checkbox"/> <b>3.</b> Mercury in straight fluorescent lamps for special purposes<br><input type="checkbox"/> <b>4.</b> Mercury in other lamps not specifically mentioned in this list<br><input type="checkbox"/> <b>5.</b> Lead in glass of cathode ray tubes, electronic components and fluorescent tubes<br><input type="checkbox"/> <b>6a.</b> Lead as an alloying element in steel containing up to 0.35% lead by weight<br><input type="checkbox"/> <b>6b.</b> Lead as an alloying element in aluminum containing up to 0.4% lead by weight<br><input type="checkbox"/> <b>6c.</b> Lead as an alloying element in copper containing up to 4% lead by weight<br><input type="checkbox"/> <b>7a.</b> Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85 % by weight or more lead)<br><input checked="" type="checkbox"/> <b>7b.</b> Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signalling, transmission as well as network management for telecommunications | <input type="checkbox"/> <b>7c.</b> Lead in electronic ceramic parts (e.g. piezoelectronic devices)<br><input type="checkbox"/> <b>8.</b> Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC amending Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances<br><input type="checkbox"/> <b>9.</b> Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators<br><input type="checkbox"/> <b>10a.</b> DecaBDE in polymeric applications<br><input type="checkbox"/> <b>10b.</b> Lead in lead-bronze bearing shells and bushes<br><input type="checkbox"/> <b>11.</b> Lead used in compliant pin connector systems<br><input type="checkbox"/> <b>12.</b> Lead as a coating material for a thermal conduction module c-ring<br><input type="checkbox"/> <b>13a.</b> Lead in optical and filter glass<br><input type="checkbox"/> <b>13b.</b> Cadmium in optical and filter glass<br><input type="checkbox"/> <b>14.</b> Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight<br><input type="checkbox"/> <b>15.</b> Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages |
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### Declaration Signature

**Instructions:** Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

## Joint Industry Guide (JIG) Material Composition Declaration for Electronic Products

Instructions: Declare whether the item substances exceed the threshold levels shown in the table and report accordingly. Where threshold levels include the words "intentionally added", substances must be declared if they are added intentionally, regardless of threshold level. For each RoHS substance, identified with dual asterisks (\*\*), report the worst case PPM at the homogeneous material level and optionally the total weight of the substance in the item. For all remaining (non-RoHS) JIG A & B substances, and any additional substances, report the total weight and optionally the PPM at the part level for each item.

				JIG A autofill - No	JIG B autofill - No	All autofill - No		
JIG	Category Name	Threshold Level	Above Threshold Level?	If yes, enter total weight and worse case PPM			Description of Use	
Level	As defined in the Joint Industry Guide	Intentionally added or PPM	Yes/No	Weight	UoM	PPM		
A	Asbestos	Intentionally Added	No		mg			
A	Certain Azo colorants	Intentionally Added	No		mg			
A	Cadmium/Cadmium Compounds **	75 PPM or Intentionally Added	No		mg			
A	Hexavalent Chromium/Hexavalent Chromium Compounds **	1000 PPM or Intentionally Added	No		mg			
A	Lead/Lead Compounds **	1000 PPM or Intentionally Added	Yes	0.000441	g	1,053	Tin/Lead Plating	
A	Lead/Lead Compounds - PVC Cables and Wires Only **	300 PPM	No		mg			
A	Mercury/Mercury Compounds **	1000 PPM or Intentionally Added	No		mg			
A	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)	Intentionally Added	No		mg			
A	Ozone Depleting Substances - Class II (HCFCs)	1000 PPM	No		mg			
A	Polybrominated Biphenyls (PBBs) **	1000 PPM or Intentionally Added	No		mg			
A	Polybrominated Diphenylethers (PBDEs) **	1000 PPM or Intentionally Added	No		mg			
A	Polychlorinated Biphenyls (PCBs)	Intentionally Added	No		mg			
A	Polychlorinated Naphthalenes ( > 3 chlorine atoms)	Intentionally Added	No		mg			
A	Radioactive Substances	Intentionally Added	No		mg			
A	Certain Shortchain Chlorinated Paraffins	Intentionally Added	No		mg			
A	Tributyl Tin (TBT) and Triphenyl Tin (TPT)	Intentionally Added	No		mg			
A	Tributyl Tin Oxide (TBTO)	Intentionally Added	No		mg			
B	Antimony/Antimony Compounds	1000 PPM	No		mg			
B	Arsenic/Arsenic Compounds	1000 PPM	No		mg			
B	Beryllium/Beryllium Compounds	1000 PPM	No		mg			
B	Bismuth/Bismuth Compounds	1000 PPM	No		mg			
B	Brominated Flame Retardants (other than PBBs or PBDEs)	1000 PPM	No		mg			
B	Nickel (external applications only)	1000 PPM	No		mg			
B	Certain Phthalates	1000 PPM	No		mg			
B	Selenium/Selenium Compounds	1000 PPM	No		mg			
B	Polyvinyl Chloride (PVC)	1000 PPM	No		mg			

**OTHER Material Composition Declaration**

**Requester Instructions:** The requester can optionally include additional substances that must be declared for the item on this form. This is in addition to JIG Level A and JIG Level B substances. The requester should enter additional substances as well as the threshold levels that specify the substance at the item level.

**Supplier Instructions:** Explicitly declare whether the item exceed the threshold level by selecting Yes or No. If the maximum concentration of any substance exceeds the threshold levels defined by the requester, then the substance content must be reported in total weight and/or worst case PPM, along with a description of material use.

JIG	Category Name	Threshold Level
Other	As defined by the Requester	Defined by the Requester
+ -		

Add Other Material Composition to JIG Tab